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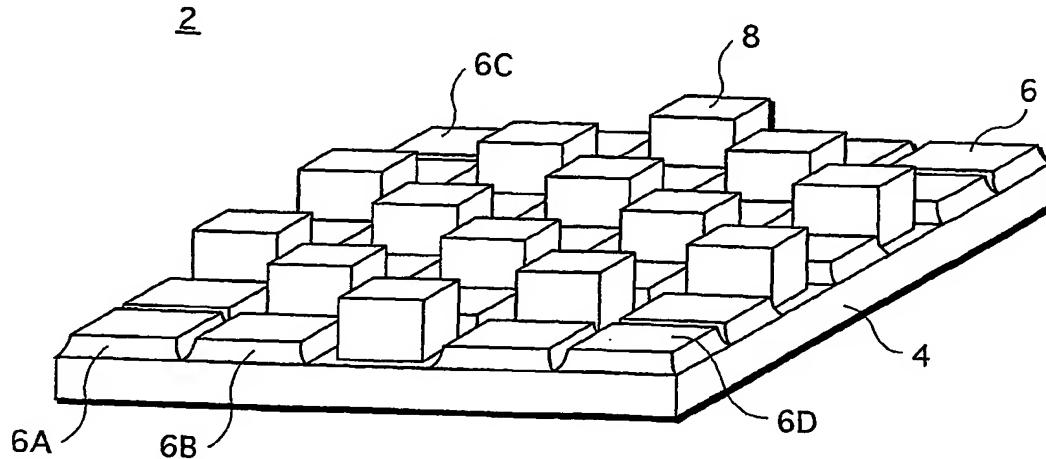
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(54) Title: SEMICONDUCTOR LIGHT EMITTING DEVICE, LIGHT EMITTING MODULE, AND LIGHTING APPARATUS



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(57) Abstract: An LED array chip (2) includes blue LEDs (6) and red LEDs (8). The blue LEDs (6) are formed by epitaxial growth on an SiC substrate (4). Bonding pads (46 and 48) are formed on the SiC substrate (4) in a wafer fabrication process. The red LEDs (8) are separately manufactured from the blue LEDs (6), and flip-chip mounted on the bonding pads (46 and 48) formed on the SiC substrate.

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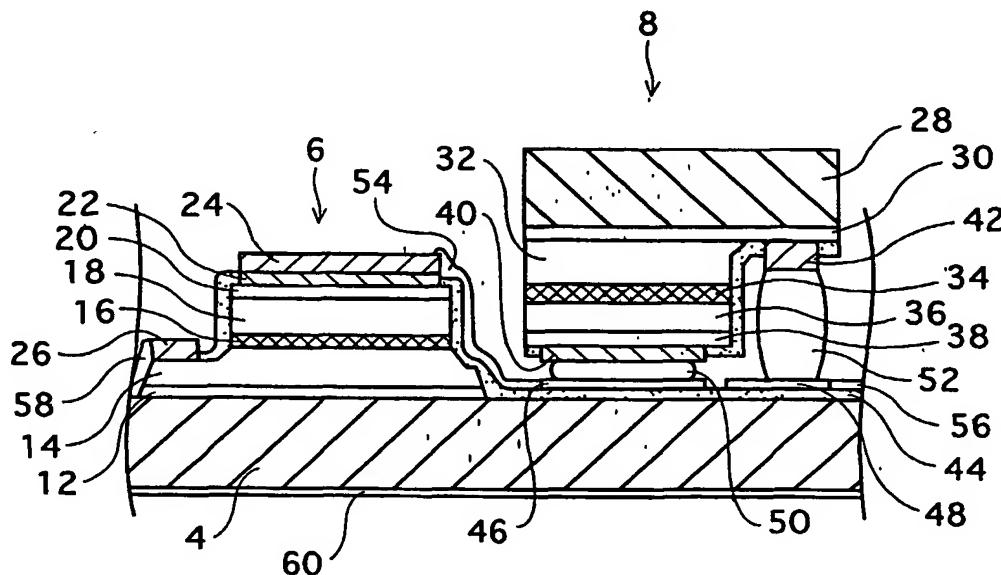
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